

### **Applications**

- General Purpose LNA/Gain Block
- · Point to Point Radio
- Electronic Warfare
- · Military & Commercial Radar
- Communications



QFN 4x4mm 24L

#### **Product Features**

• Frequency Range: 2 - 20 GHz

P<sub>SAT</sub>: 22 dBmP<sub>1dB</sub>: 19 dBm

Small Signal Gain: 17 dBAdjustable Gain RangeOutput TOI: 29 dBm

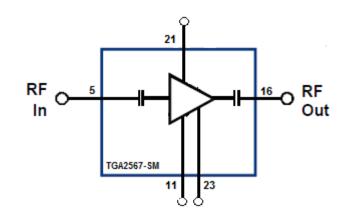
Noise Figure: 2 dB

• Bias:  $V_D = 5 \text{ V}$ ,  $I_{DQ} = 100 \text{ mA}$ ,  $V_{G1} = -0.7 \text{ V}$ ,  $V_{G2} = +1.3 \text{ V}$  Typical

 $\bullet$  ESD Protection Circuitry on  $\,V_D\,,\,V_{G1}$  and  $\,V_{G2}$ 

• Package Dimensions: 4.0 x 4.0 x 1.42 mm

### **Functional Block Diagram**



#### **General Description**

TriQuint's TGA2567-SM is a LNA Gain Block fabricated on TriQuint's proven 0.15um pHEMT production process.

The TGA2567-SM operates from 2 to 20 GHz and typically provides 19 dBm of 1dB compressed output power with 17 dB of small signal gain. Greater than 16 dB of adjustable gain can be achieved by varying  $V_{\rm G2}$ . The Noise Figure is typically 2 dB at mid band

The TGA2567-SM is available in a low-cost, surface mount 24 lead 4x4 AIN QFN package base with an Air cavity LCP lid. TGA2567-SM is ideally suited to support both commercial and defense related applications.

Lead-free and RoHS compliant.

Evaluation Boards are available upon request.

### **Pad Configuration**

Pad No.	Symbol
1,2,4,6,7,12,13,15,17- 19,24,25	GND
3,8-10,14,20,22	N/C
5	RF IN
11	V <sub>G1</sub>
16	RF OUT
21	V <sub>D</sub>
23	$V_{G2}$

# **Ordering Information**

Part	<b>ECCN</b>	Description
TGA2567-SM	EAR99	2 – 20 GHz LNA / Gain Block



### **Absolute Maximum Ratings**

Parameter	Value
Drain Voltage (V <sub>D</sub> )	6 V
Drain to Gate Voltage $(V_D-V_{G1})$	8 V
Gate Voltage Range (V <sub>G1</sub> )	-2 to 1 V
Gate Voltage Range (V <sub>G2</sub> )	-2 to +4 V
Drain Current (I <sub>D</sub> )	160 mA
Gate Current (I <sub>G1</sub> , I <sub>G2</sub> )	-1 to 40 mA
Power Dissipation (P <sub>DISS</sub> )	2.8 W
RF Input Power, CW, 50 $\Omega$ , T = 25 °C (P <sub>IN</sub> )	+22 dBm
Channel Temperature (T <sub>CH</sub> )	200 °C
Mounting Temperature (30 Seconds)	260 °C
Storage Temperature	-55 to 150 °C

Operation of this device outside the parameter ranges given above may cause permanent damage. These are stress ratings only, and functional operation of the device at these conditions is not implied.

### **Recommended Operating Conditions**

Parameter	Value
Drain Voltage (V <sub>D</sub> )	5 V
Drain Current (I <sub>DQ</sub> )	100 mA
Gate Voltage (V <sub>G1</sub> )	-0.7 V (Typ.)
Gate Voltage (V <sub>G2</sub> )	1.3 V

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

# **Electrical Specifications**

Test conditions unless otherwise noted: 25 °C,  $V_D = 5$  V,  $I_{DQ} = 100$  mA ,  $V_{G1} = -0.7$  V,  $V_{G2} = 1.3$  V

Parameter	Min	Typical	Max	Units
Operational Frequency Range	2		20	GHz
Small Signal Gain		17		dB
Input Return Loss		15		dB
Output Return Loss		14		dB
Output Power at Saturation		22		dBm
Output Power at P1dB		19		dBm
Output TOI		29		dBm
Noise Figure		2		dB
Gain Temperature Coefficient		0.013		dB/°C
Noise Temperature Coefficient		0.009		dB/°C

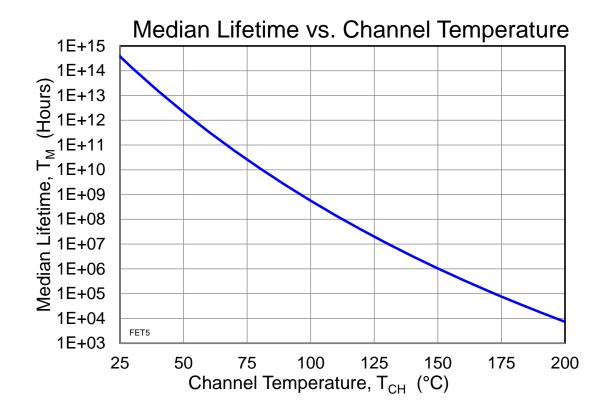


Thermal	and Reliabi	lity Information

Parameter	Test Conditions	Value	Units
Thermal Resistance, $\theta_{JC (1)}$	Tbaseplate = 85 °C	41	°C/W
Channel Temperature, T <sub>CH</sub> (Without RF Drive)	Tbaseplate = 85 °C, V <sub>D</sub> = 5 V,	106	°C
Median Lifetime, T <sub>M</sub> (Without RF Drive)	$I_{DQ} = 100 \text{ mA}, P_{DISS} = 0.5 \text{ W}$	2.4 x 10^8	Hrs
Channel Temperature, T <sub>CH</sub> (Under RF Drive)	Tbaseplate = 85 °C, $V_D = 5 V$ ,	109	°C
Median Lifetime, T <sub>M</sub> (Under RF Drive)	$I_{DD}$ = 156 mA, $P_{OUT}$ = 22.8 dBm, $P_{DISS}$ = 0.59 W	1.6 x 10^8	Hrs

Notes: (1) Thermal resistance measured to back of package.

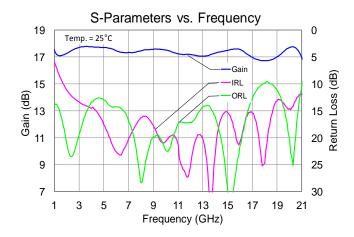
# **Median Lifetime**

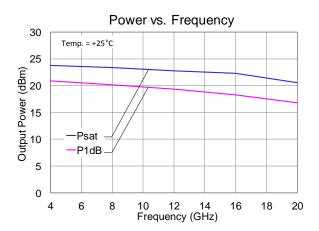


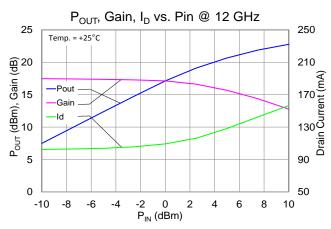


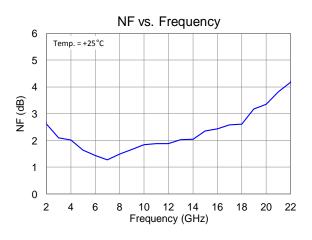
# **Typical Performance**

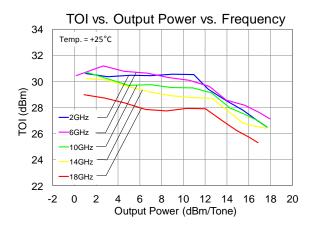
Conditions unless otherwise specified:  $V_D = 5 \text{ V}$ ,  $I_{DQ} = 100 \text{ mA}$ ,  $V_{G1} = -0.7 \text{ V}$  Typical,  $V_{G2} = 1.3 \text{ V}$ .

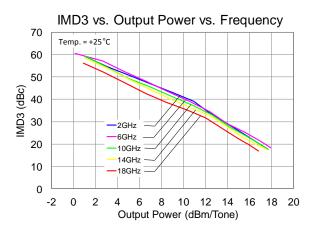








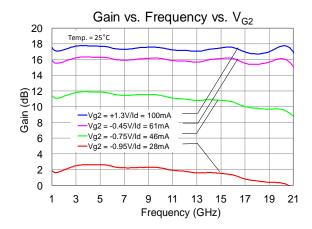


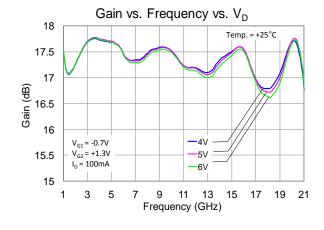


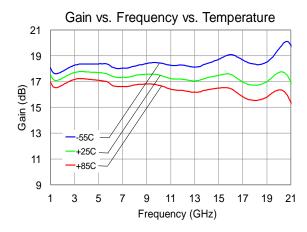


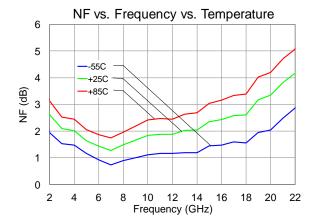
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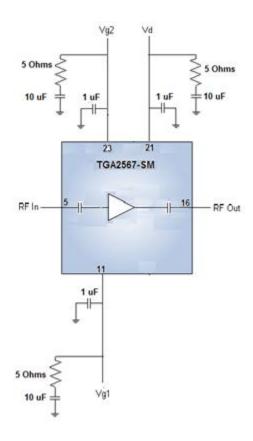








### **Application Circuit**



Notes: To prevent damage to the device due to overshoot or oscillation issues, we recommend that current limits for all power supplies are set properly for each power supply before applying the voltage. The following are recommended current limits for each power supply:

Set 10 mA current limit to  $V_{G1}$  and  $V_{G2}$  Set 140 mA current limit to  $V_{D}$ 

### **Bias-up Procedure**

- 1. Apply -1.5 V to V<sub>G1</sub>.
- 2. Apply +5 V to V<sub>D.</sub>
- 3. Apply  $+1.3 \text{ V to V}_{G2}$ .
- 4. Adjust  $V_{G1}$  until  $I_{DQ}$  = 100 mA ( $V_{G1} \sim -0.7$  V Typ.).
- 5. Turn On RF supply.
- 6. Adjust V<sub>G2</sub> to obtain desired gain

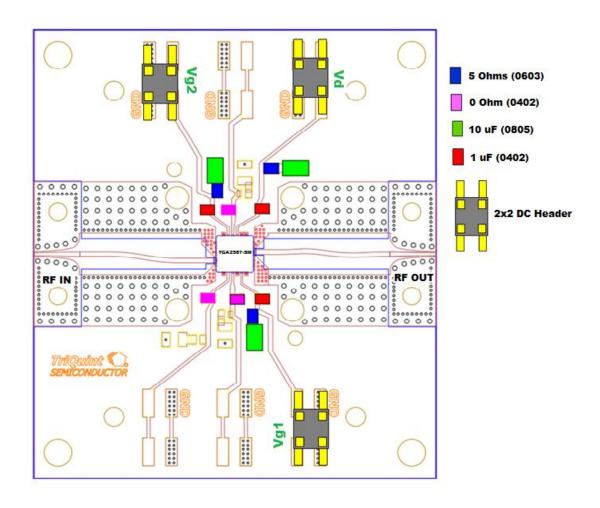
#### **Bias-down Procedure**

- 1. Reduce  $V_{G2}$  to +1.3 V.
- 2. Turn off RF supply.
- 3. Reduce  $V_{G1}$  to -1.5 V. Ensure  $I_{DQ} \sim 0$  mA
- 4. Set  $V_{G2}$  to 0 V.
- 5. Set  $V_D$  to 0 V.
- 6. Set V<sub>G1</sub> to 0 V.



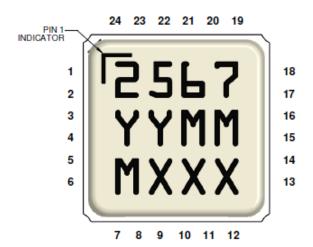
### **Recommended Board Layout Assembly**

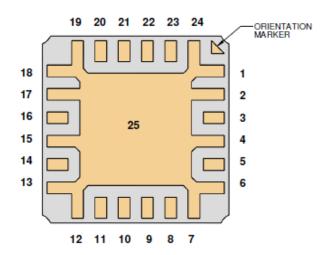
Top dielectric material is ROGERS 4350, 0.010 inch thickness with 0.5 oz copper.





## **Pin Layout**





# **Pin Description**

Pin	Symbol	Description
1,2,4,6,7,12,13,15,17-19,24, 25	GND	Backside paddles; must be grounded on PCB. Multiple vias should be employed to minimize inductance and thermal resistance. (2)
3,8-10,14,20,22	N/C	No internal connection; must be grounded on PCB.
5	RF IN	RF input
11	$V_{G1}$	Gate voltage. Bias network is required. (1)
16	RF OUT	RF output.
21	V <sub>D</sub>	Drain voltage. Bias network is required. (1)
23	$V_{G2}$	Gate voltage. Bias network is required. (1)

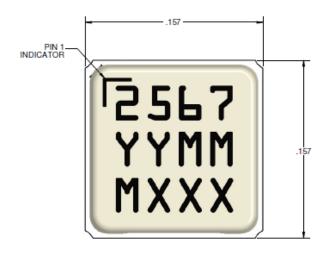
#### Notes:

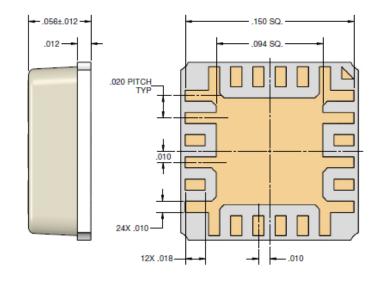
- 1. See Application Circuit on page 6 as an example.
- 2. See Mounting Configuration on page 9 for suggested footprint.



#### **Mechanical Information**

All dimensions are in inches. Unless specified otherwise, tolerances: ± 0.127 in.





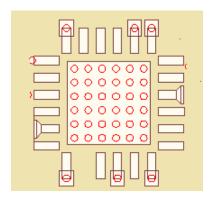
Marking: Part number – 2567 Year/Month code – YYMM Batch ID – MXXX Package Materials:

Base Aluminum Nitride (AIN) Lid Liquid Crystal Polymer (LCP)

Part is EPOXY Sealed

Land Pads are Gold Plated

# **PCB Mounting Pattern**



The pad pattern shown above has been developed and tested for optimized assembly at TriQuint. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company, careful process development is recommended.

Ground / thermal vias are critical for the proper performance of this device. Vias should use a 0.008 in. diameter drill, and they are solid filled, copper plated shut.



### **Product Compliance Information**

#### **ESD Sensitivity Ratings**



Caution! ESD-Sensitive Device

ESD Rating: TBD Value: TBD

Test: Human Body Model (HBM)
Standard: JEDEC Standard JESD22-A114

### **MSL Rating**

Level TBD at +260 °C convection reflow The part is rated Moisture Sensitivity Level TBD at 260°C per JEDEC standard IPC/JEDEC J-STD-020.

#### **Solderability**

Compatible with the latest version of J-STD-020, Lead free solder, 260°C

#### **RoHs Compliance**

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

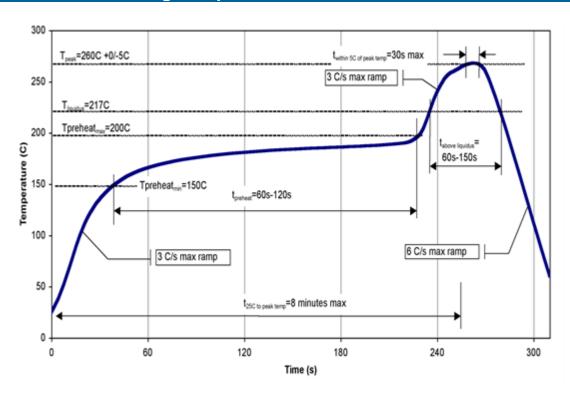
This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>0<sub>2</sub>) Free
- PFOS Free
- SVHC Free

#### **ECCN**

US Department of Commerce: EAR99

### **Recommended Soldering Temperature Profile**







#### **Contact Information**

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

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